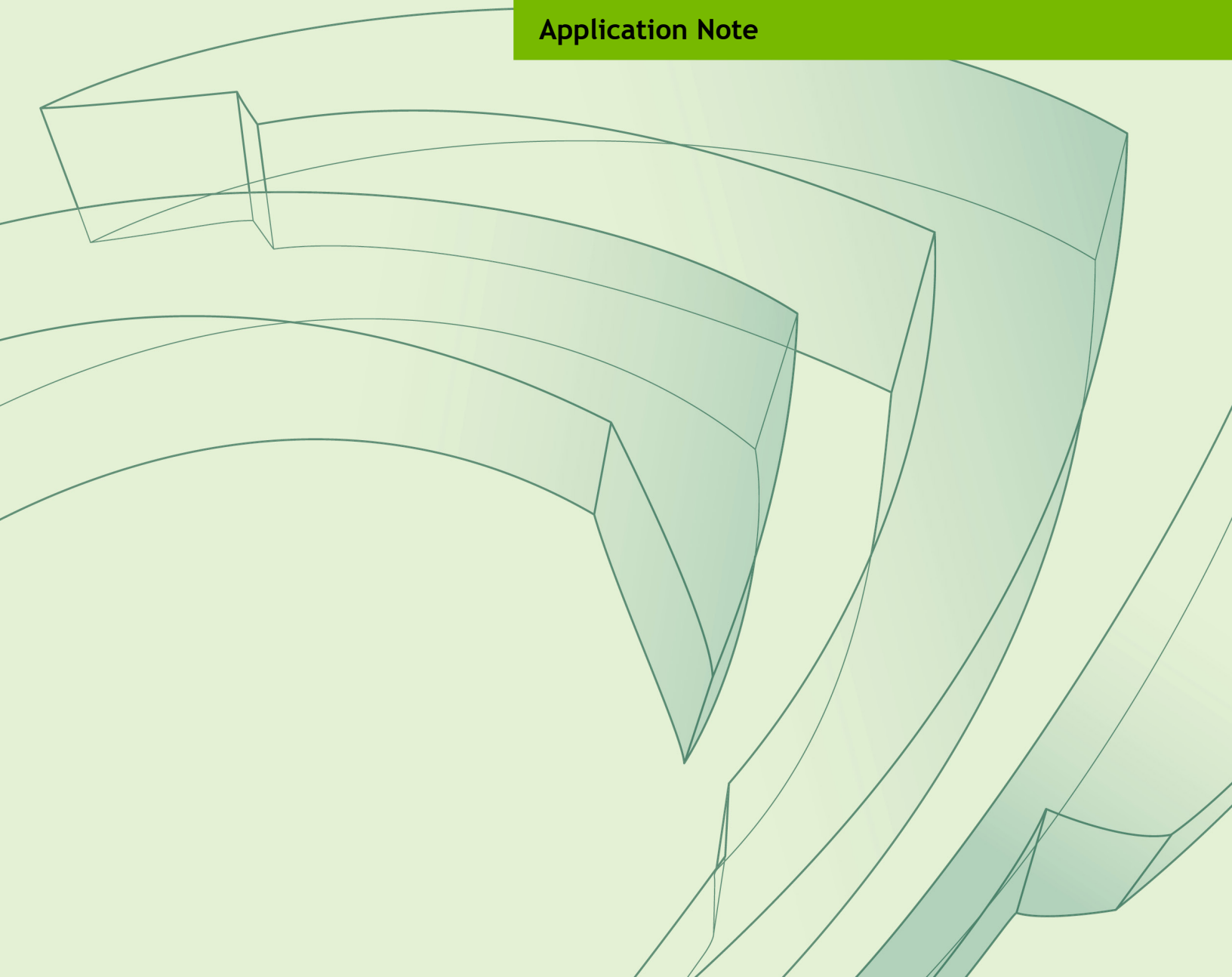




# JETSON AGX XAVIER SERIES FUSE SPECIFICATION

DA-09342-001\_v1.1 | June 2021

**Application Note**



## DOCUMENT CHANGE HISTORY

DA-09342-001\_v1.1

Version	Date	Description of Change
1.0	February 19, 2019	Initial Release
1.1	June 22, 2021	Added note to “Introduction” regarding references to Jetson AGX Xavier series modules

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# INTRODUCTION

This application note provides a technical overview of the issues and considerations related to the NVIDIA® Jetson™ AGX Xavier™ Series Fuse Specification.



**Note:** References to Jetson AGX Xavier applies to any of the Jetson AGX Xavier series of modules. This includes Jetson AGX Xavier Industrial (JAXi).

Jetson AGX Xavier module includes customer/Original Device Manufacturer (ODM)-programmable fuses which are used to store security keys and ODM system design configuration options. Fuses are divided into 2 distinct areas:

- ▶ Manufacturing Fuses (for example, security keys, boot options, etc.)
- ▶ ODM Field Fuses (for example, defined by ODM software for rollback protection, IDs, etc.)

All fuses default values are Logic 0 when not burned. After they are burned, they represent Logic 1.

## ECC

Individual fuses can fail with very low probability and the fuse logic corrects these failures by using redundancy techniques:

- ▶ An OR-ECC, where two fuses are ORed together to get the corrected value. This code is unidirectional and protects against a 1b becoming a 0b.
- ▶ A block code ECC, based on a CRC, applied to a set of fuses. The ECC is able to correct one error in the set of protected fuses combined with very good error detection when more than one errors are present. This ECC has much less overhead than the OR-ECC but requires groups of bits to be burned together.

Both ECC methods are transparent to software when using fuse option registers to get access to fuse information but requires some care when burning fuses.

# SYSTEM REQUIREMENTS

Jetson AGX Xavier contains all the power and logic to program the onboard fuses. The system designer does not have to make any provision on their own system design.



**Note:** The voltage supplied to the module should not be removed during burning.

# FUSE VARIABLES

Jetson AGX Xavier contains 2 types of fuses for ODM use. Those that configure the device and should be burned during the manufacturing process before the product is released to the end user, and those that may be burned during the lifetime of the product by the ODM for software to use.

An example of each of these is:

- ▶ ODM manufacturing fuses
  - Boot keys
  - Boot device
  - Product serial number
- ▶ ODM field programmable fuses
  - Date of first use
  - OTA information



## MANUFACTURING PROGRAMMABLE FUSES

Jetson AGX Xavier contains multiple manufacturing fuses that control different items for security and boot. These fuses should be burned during the manufacturing process. The ODM Production Mode fuse (also known as “Security Mode”) should always be burned by the ODM on the manufacturing line before the product is shipped to the end user. This fuse acts as a master lock for all the manufacturing fuses. Once burned it locks the values of the other manufacturing fuses. They cannot be burned once the ODM Production Mode fuse has been burned.

Table 1 summarizes available fuse settings and values for each.



**Note:** All ODM fuses have the value of ZEROs when shipped to an ODM.



**CAUTION:** Burning a fuse (changing the value of a fuse from 0 to 1) is non-reversible. Once a fuse bit is burned (set to 1), you cannot change the fuse value from 1 to 0. For example: A value of 1 (0x0001) can be changed to 3 (0x0011) or 7 (0x0111). It cannot, however, be changed to a value of 4 (0x0100) since bit zero is already burned to 1.

The burning of fuses should be done without a system reset between different phases.

The eMMC/UFS must be powered and pins associated with eMMC/UFS should not be driven externally during the fuse burning process if either of the following condition holds true:

1. It is a boot device.
2. RPMB provisioning is being done on this device along with fuse burning.

Table 1. Fuse Names and Descriptions

Fuse Name	Fuse Description	Bit Length	Notes
FUSE_SECURITY_MODE [0]	<b>ODM Production Mode</b> Also known as Security Mode. This fuse write-protects all manufacturing device fuses against any further fuse burning and also hides the SBK values. <b>This fuse must be burned last.</b>	1	
FUSE_ARM_JTAG_DIS [0]	<b>ARM JTAG Disable</b> Completely disables the external debug paths, including ARM JTAG path and USB SWD path. This field complements the ARM debug authentication field.	1	Note 3

Fuse Name	Fuse Description	Bit Length	Notes
FUSE_DEBUG_AUTHENTICATION [4:0]	<b>ARM Debug Authentication</b> Provides fine control of ARM debug capabilities Burning one of these fuses permanently disables the equivalent debug capability: <ul style="list-style-type: none"> <li>• Bit 0 forces dbgen to 0</li> <li>• Bit 1 forces niden to 0</li> <li>• Bit 2 forces spiden to 0</li> <li>• Bit 3 forces spniden to 0</li> <li>• Bit 4 forces deviceen to 0</li> </ul>	5	Note 3
FUSE_PRIVATE_KEY0 [31:0] /.../ FUSE_PRIVATE_KEY3 [31:0]	<b>Secure Boot Key (SBK)</b> Stores an ODM-supplied secure boot key for each chip. Use of SBK and the authentication scheme are selected via fuse_boot_security_info. Example: "0xABCDEF" input value will be represented as "0x0000000000000000000000000000ABCDEF"	128	Note 1, 3, 4
FUSE_PUBLIC_KEY0 [31:0] /.../ FUSE_PUBLIC_KEY7 [31:0]	<b>Public Key Hash (PKC)</b> These eight consecutive registers encode a 256-bit hash of the ODM public key.	256	Note 3
FUSE_EK0 [31:0] /.../ FUSE_EK7 [31:0]	<b>Endorsement Key</b> This key might be burning in encrypted form, with decryption performed by boot ROM.	256	Note 3
FUSE_RESERVED_SW [23:0]	<b>Reserved Bits for Software (read by Boot ROM)</b> Bit [2:0] Boot Device Select - Identifies the OS image boot device Bit [3] If set, will boot using the device selected in Bits 2:0 Bit [4] Reserved Bit [5] Enable Watchdog Bit [6] Reserved Bit [7] RCM SS Mode Enable - option to enable USB RCM to use SS transfer mode Bit [8] Reserved Bit [9] Reserved Bit [10] Enable Low Batt check and stall boot if SOC_GPIO02 is pulled low Bit [23] Disable entry into RCM mode	24	Note 3
FUSE_BOOT_DEVICE_INFO [23:0]	<b>Boot Device Configuration</b> Identifies the OS image boot device configuration. Used in conjunction with the Boot Device Selection to provide its configuration.	24	Note 2,3

Fuse Name	Fuse Description	Bit Length	Notes
FUSE_BOOT_SECURITY_INFO [15:0]	<b>Boot Security Info</b> Bits interpreted by boot software with following mapping: Bits [1:0] mapped to Secure Boot Authentication Scheme, where 00b: SHA2 Hash 01b: 2048 bit RSA 10b: 3072 bit RSA 11b: ECC (Elliptic Curve, see also bit 7) Bit [2] secure boot encryption scheme, enables encryption using SBK when set to 1 Bit [3] ODM FEK usage enable Bits [6:4] ODM Fuse Encryption Key Select Bit [7] only used if bit 1:0 is set to 11b (elliptic) 0b = ECDSA with NIST P256 curve 1b = EdDSA (Ed25519) Bits not listed are reserved	16	Note 3
FUSE_SECURE_PROVISION_INFO [1:0]	<b>Factory Secure Provisioning</b> Allows the ODM to control secure provisioning features: [0] is hide bit; [1] is test_part bit. The hide bit ([0]) should be burned *before* burning SBK fuses if the Factory Secure Provisioning feature is being used.	2	Note 3
FUSE_CCPLX_DFD_ACCESS_DISABLE[0]	<b>CCPLEX Low-Level DFD Access Disable</b> CPLEX power management DFD Disable access (when fuse is burned, DFD access is disabled).	1	Note 3
FUSE_KEK00 [31:0] FUSE_KEK01 [31:0] FUSE_KEK02 [31:0] FUSE_KEK03 [31:0] FUSE_KEK10 [31:0] FUSE_KEK11 [31:0] FUSE_KEK12 [31:0] FUSE_KEK13 [31:0] FUSE_KEK20 [31:0] FUSE_KEK21 [31:0] FUSE_KEK22 [31:0] FUSE_KEK23 [31:0]	<b>Key Encryption Key or Key Seed</b> These 12 consecutive registers can be used to encode some Key Encryption Key and/or some Key Seed, with different combinations of width.	384	Note 3
FUSE_ODM_INFO [15:0]	<b>ODM Info</b> No predefined use, free to use by ODM.	16	Note 3
FUSE_ODMID0 [31:0] FUSE_ODMID1 [31:0]	<b>ODM ID</b> These 2 consecutive registers encode a 64-bit ODM ID.	64	Note 3

Fuse Name	Fuse Description	Bit Length	Notes
FUSE_H2 [31:0]	<b>Hamming Code</b> Implement the ECC for the ODM manufacturing fuses. <b>This fuse must be burned just before burning ODM Production Mode.</b>	32	Notes 3, and 5
FUSE_FORCE_DEBUG_WITH_TEST_KEYS [0]	<b>Debug with Test Keys Enable</b> Enable the use of test keys when debug is allowed (to protect production key)	1	Note 3
FUSE_FLW2 [0]	<b>Force Large Weight</b> This bit is used as part of the ECC scheme, burning to 1 to insure field H2 has large enough weight.	1	Note 3
FUSE_OPT_USB2NVJTAG_DISABLE [0]	Disable the USB debug path, note that this is independent of FUSE_ARM_JTAG_DIS	1	Note 3

**Notes:**

1. SBK will be used to decrypt the bootloader and Boot Config Table if encryption is enabled through boot\_security\_info fuse.
2. See the boot options fuse configuration table (Table 4) for the correct Boot settings for your platform.
3. Fuse burning of ODM manufacturing programmable fuses is disabled when ODM Production Mode fuse = 1.
4. After burning the value and rebooting the chip, the value is an input to the SSK calculation regardless of whether the ODM Production Mode fuse has been set.
5. Burning of these fuses will be done by NVIDIA software.

## ODM Production Fuse

The ODM production fuse is a global lock of all the manufacturing fuses. During the manufacturing process, software should program all other manufacturing fuses, then update the CRC ECC field (**FUSE\_H2**, this may require to also update the **FUSE\_FLW2** field), then program the ODM production fuse last. A reset is required for the lock to take into effect.

## Debug Disable

There are three fuses which impact the ability to debug Jetson AGX Xavier ARM processors.

## ARM\_JTAG\_DISABLE

When burned, this fuse permanently prevents any JTAG access to the debug access port that occurs through the JTAG pins on the module. This prevents any JTAG access by external ARM debuggers during normal product lifetime. This also disables the USB SWD debug path.



**Note:** Boundary Scan is still possible through the JTAG pins irrespective of this fuse state.

## CCPLEX\_DFD\_ACCESS\_DISABLE

When this fused is burned, NVIDIA internal CCPLEX debug access is disabled on the chip. Burning this fuse will prevent NVIDIA from performing any hardware level debug on the CCPLEX, should it be required.

## ARM Debug Authentication Signals

These fuses control the standard ARM debug authentication signals. Each fuse forces the corresponding signal to 0 (disabled). Table 2 describes the ARM debug authentication signals.

Table 2. ARM Debug Authentication Signals

Signal Name	Description	Definition	Common Use Case
DBGEN	<b>Debug Enable</b> When asserted, enables invasive and non-invasive debug of non-secure state. Note that when DBGEN is not asserted access to debug components is generally still permitted, but those components are disabled.	NonSecure Invasive Debug Enable	CPUs to halt AXIAP to make system accesses ETR to stream trace to DRAM
NIDEN	<b>Non-Invasive Debug Enable</b> When asserted, enables non-invasive debug operations, such as trace, of non-secure state. NIDEN can be asserted independently of DBGEN.	NonSecure Non Invasive Debug Enable	PTM trace from CPUs
SPIDEN	<b>Secure Privileged Invasive Debug Enable</b> When asserted along with DBGEN, enables invasive and non-invasive debug of Secure state.	Secure Invasive Debug Enable	AXI_AP to make secure accesses into the system ETR to write to Secure DRAM

Signal Name	Description	Definition	Common Use Case
SPNIDEN	<b>Secure Privileged Non-Invasive Debug Enable</b> When asserted along with NIDEN, enables non-invasive debug of Secure state.	Secure Non Invasive Debug Enable	Accessing Secure registers in PMU and CPUs over the Debug APB
DEVICEEN	<b>Device Debug Enabled</b> Enables the external debug tools connection to the device. This signal also drives the DBGSWENABLE which is an enable input signal of the CoreSight Components and Cortex-A Series processor.	Device Enable	Accessing any registers mapped over the Debug APB

## Secure Boot Key

These fuses should be burned with the Secure Boot Key if SBK is being used. The SBK values are hidden once the ODM production mode fuse has been burned.

## Public Key Hash

These fuses should be burned with the hash of the ODM public key.

## Skip Boot Device Selection Straps

This fuse determines if the boot device selection is determined by the straps or by the fuse settings.

Jetson AGX Xavier is supplied as configured to boot from straps. For production devices it is recommended that the fuses are used to select the boot device and this fuse should be burned. When this fuse is burned then the boot device is determined by the settings of the “Boot Device Selection” fuses.

## Boot Device Selection

Jetson AGX Xavier uses eMMC for boot. These fuses should remain at their default (0x0 = eMMC).

Table 3. Boot Selection (FUSE\_RESERVED\_SW [2:0])

Register	Description	Values
FUSE_RESERVED_SW [2:0]	Boot Device Select	0x0 = eMMC

## Boot Device Information

These fuses determine parameters for the boot device. Jetson AGX Xavier uses eMMC for boot. These fuses should be burned to 0x3 if boot fuses are to be burned.

Table 4. Boot Device Configuration (FUSE\_BOOT\_DEVICE\_INFO[7:0] eMMC Only)

Fuse Bits	Device	Description	Values (Default = 0x0)
7:0	eMMC	Data Rate: SDR Clk: 51 MHz MultiPage Support: READ_MULTIPLE	0x00
		Data Rate: SDR Clk: 25.5 MHz MultiPage Support: READ_MULTIPLE	0x01
		Data Rate: SDR Clk: 25.5 MHz MultiPage Support: READ_SINGLE	0x02
		Data Rate: DDR Clk: 51 MHz MultiPage Support: READ_MULTIPLE	0x03
		Data Rate: DDR Clk: 25.5 MHz MultiPage Support: READ_MULTIPLE	0x04

## ODM FIELD PROGRAMMABLE FUSES

The following fuses are available for the system designer to use for burning during the product lifetime. If these fuses are to be altered, the module power supplies must be present throughout the fuse burning.

The **RESERVED\_ODM** fuses are split into 12 banks of 32 bits. The first of these 4 banks (0-3) can be locked out by setting the corresponding bit in the ODM Lock fuse (for example, to lock **RESERVED\_ODM** Bank 1, then ODM LOCK Bit [1] should be set.). This will prevent any unintentional burning of other bits in this bank.

**RESERVED\_ODM** Banks 4-11 do not have this lock feature.

Table 5. Field Programmable Fuses

Fuse Name	Fuse Description	Bit Length
<b>Reserved_ODM</b> (FUSE_RESERVED_ODM0 [31:0]) /.../ (FUSE_RESERVED_ODM11 [31:0])	The consecutive registers are reserved for the customer use, including ODM/software versioning. These fuses are field programmable, Reserved_ODM{0:3} can be individually locked against further burning using corresponding bits in ODM_Lock, bit [b] locks Reserved_ODM{b}.	384
<b>ODM_lock</b> (FUSE_ODM_LOCK [3:0])	ODM_lock[i] disables further changes to the i-th 32 bits subset of the reserved ODM field. Applicable to the first four subsets only. FUSE_ODM_LOCK [0] = Reserved_ODM[0] FUSE_ODM_LOCK [1] = Reserved_ODM[1] FUSE_ODM_LOCK [2] = Reserved_ODM[2] FUSE_ODM_LOCK [3] = Reserved_ODM[3]	4



**Note:** Refer to the *Jetson Platform Fuse Burning and Secure Boot Documentation and Tools* for information on how to program the fuses.



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